EB3000

Performance-boosting HPC Accelerator,
Gear up for the Future of Computing

An All-in-one Solution

Designed with performance-driven features, the HPC accelerator extends PCIe Gen4 connectivity with 16 PCIe x16 slots, allowing you to install many add-in-cards in one chassis to get ready for tomorrow's AI and HPC.

Application

- Hyperscale Data Center
- High Performance Computing
- AI and Machine Learning

Right Configuration to Meet Needs

This highly flexible HPC accelerator supports multiple configurations of PCIe devices, such as graphic cards, FPGA accelerator cards and AI accelerator cards, meeting challenging demands of a variety of applications and maximizing application performance.

Faster than Ever

Purpose-built for accelerating AI/HPC applications, the chassis can be equipped with up to 4 high-bandwidth NICs, along with its innovative hardware design, guaranteeing faster result for business to make timely decisions.

- AI/HPC Applications
- Up to 8 Double-width Cards
- Up to 4 Network Interface Cards
- 2+1 Redundancy, Platinum Level
- 3U Rackmount

ingrasys®

EB3000

Specifications

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Expansion Slots

- **Total**
  16 x PCIe Gen4 x16 Slots
- **Front Side**
  8 x Double-width FH 3/4L PCIe Cards
  4 x Single-width FH 3/4L PCIe Cards
- **Rear Side**
  4 x NIC Cards

Rear Panel

1 x Power LED / 1 x UID LED / 1 x System Health LED
1 x RJ45 Port for 1GbE Ethernet
4 x zCD Connectors (4 x PCIe Gen4 x16 Upstream Ports)

Chassis Dimension (H x W x D)

5.1” x 17.0” x 32.28” /
130.8mm x 436.0mm x 820.0mm

AC Input

180Vac ~ 264Vac,
164Vdc ~ 320Vdc,
50-60Hz

Management

1 x ASPEED AST2500

PSUs

2+1 Redundant 2400W Platinum Power Supplies

Fans

12 x 60*56mm for N+1 Cooling Redundancy

Form Factor

3U Rackmount

Operating Temperature

5°C to 35°C (41°F to 95°F)

Non-operating Temperature

-40°C to 70°C (-40°F to 158°F)

Operating Relative Humidity

8% to 85%RH

Non-operating Relative Humidity

5% to 95%RH